

## Material Set Change:

Package Material Set		Carsem	ASE Chungli
SOIC_N	Die Attach	Ablestik 84-1LMISR4	Hitachi EN-4900GC
	Mold Compound	Sumitomo G600	Sumitomo G700LY
	Wire	1.3 mil Gold Wire	1.3mil Gold Wire

# ADuM3211 Die Revision and Assembly Site Transfer

## Qualification Results Summary of ADuM3211

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	<b>Passed</b> ±1250V
Electrostatic Discharge <i>Human Body Model</i>	JEDEC <i>JESD22-A114</i>	3/voltage	<b>Passed</b> ±2500V
Latch-Up	JEDEC <i>JESD78</i>	1 x 15	<b>Passed</b> ±200mA @ +8.25V
Solder Heat Resistance (SHR) <sup>1</sup>	JEDEC <i>J-STD-020</i>	1 x 30	<b>PASS</b>

<sup>1</sup>Preconditioned per JEDEC J-STD-020 Level 1